

REMARKS

Claims 1-18 are pending in this application. By this Amendment, claims 1 and 5 are amended. No new matter is added. Support for the amendments to claims 1 and 5 may be found at, for example, page 7, lines 6-22 of the original specification (which corresponds to paragraph [0060] of US 2004-0232540 A1).

I. Information Disclosure Statement

Applicant thanks the Examiner for the acknowledgement that the references cited in the March 1, 2004 and September 28, 2005 Information Disclosure Statements have been considered. Applicant requests the Examiner to also acknowledge consideration of the references cited in the November 21, 2005 Information Disclosure Statement.

II. Rejections Under 35 U.S.C. §103(a)

Claims 1-5, 8, 11, 14, 17 and 18 are rejected under 35 U.S.C. §103(a) over JP 01-164044 (JP 044); and claims 6, 7, 9, 10, 12, 13, 15 and 16 are rejected under 35 U.S.C. §103(a) over JP 044 as applied to claims 1-5, 8, 11, 14, 17 and 18 and further in view of U.S. Patent No. 6,625,032 (Ito). These rejections are respectfully traversed.

Claim 1 recites a metal layer formed of a plurality of layers including a diffusion prevention layer in contact with the pad and an uppermost layer being less oxidizable than the pad.

Claim 5 recites a step of forming a metal layer of a plurality of layers including a diffusion prevention layer in contact with the pad and an uppermost layer being less oxidizable than the pad.

These features of claims 1 and 5 are not taught or suggested by JP 044. JP 044 merely discloses an electrode land portion formed of a single layer of Al or Au. JP 044 fails to disclose, teach or suggest an electrode land portion formed of a plurality of layers as recited in claims 1 and 5.

The recitation in claim 1 of a metal layer formed of a plurality of layers including a diffusion prevention layer in contact with the pad and an uppermost layer being less oxidizable than the pad, and the recitation in claim 5 of forming such a layer, allows for prevention of any diffusion of an interconnect formed above the uppermost layer of the metal layer into the base material of the chip component, which provides a more reliable semiconductor device. This benefit is not taught or suggested by the electrode land portion formed of a single layer, as disclosed by JP 044.

Ito is merely relied upon for allegedly teaching a dispersant ejecting method.

For the foregoing reasons, claims 1 and 5, as well as the claims depending therefrom, are not rendered obvious by JP 044 and/or Ito.

Withdrawal of the rejections is respectfully requested.

III. Double Patenting Rejection

Claims 1-18 are provisionally rejected on the ground of nonstatutory obviousness-type double patenting over claims 1-34 of co-pending U.S. Application No. 10/788,499 in view of JP 044. This rejection is respectfully traversed.

U.S. Application No. 10/788,499 and JP 044 each fail to teach or suggest a metal layer formed of, or forming a metal layer of, a plurality of layers including a diffusion prevention layer in contact with the pad and an uppermost layer being less oxidizable than the pad, as recited in claims 1 and 5 and as discussed above.

For the foregoing reasons, claims 1 and 5, as well as the claims depending therefrom, are not rendered obvious by claims 1-34 of U.S. Application No. 10/788,499 in view of JP 044.

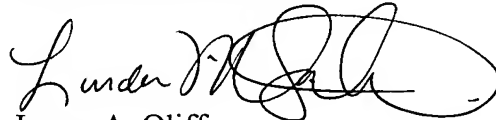
Withdrawal of the rejection is respectfully requested.

IV. Conclusion

In view of the foregoing, it is respectfully submitted that this application is in condition for allowance. Favorable reconsideration and prompt allowance of the pending claims are earnestly solicited.

Should the Examiner believe that anything further would be desirable in order to place this application in even better condition for allowance, the Examiner is invited to contact the undersigned at the telephone number set forth below.

Respectfully submitted,



James A. Oliff
Registration No. 27,075

Linda M. Saltiel
Registration No. 51,122

JAO:LMS/eks

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OLIFF & BERRIDGE, PLC
P.O. Box 19928
Alexandria, Virginia 22320
Telephone: (703) 836-6400

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